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(54) Title: **COATING COMPOSITIONS COMPRISING EPOXY RESINS AND AMINOFUNCTIONAL SILICONE RESINS**

(57) Abstract: This invention relates to a coating composition comprising (A) 100 weight parts of at least one epoxy resin; (B) 3-300 weight parts of at least one aminofunctional silicone resin; (C) up to 50 weight parts of at least one organic hardener; (D) up to 100 weight parts of at least one epoxyfunctional silicone resin; and (E) up to 10 weight parts of at least one cure accelerator. The coating compositions of this invention have acceptable moduli (>100MPa), are tough, flexible, solvent and water resistant over a broad temperature range.

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